

LINEAR TECHNOLOGY MATERIALS DECLARATION

LTC3631IDD-3.3#PBF

(Engineering Calculation)

DFN 3mm X 3mm Exp. Pad

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TOTAL MASS (g):

0.02214238

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000726	1000000	32787.81		
Die Coat	Dow Corning	Silicone	67762-90-7	0	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.00935	975000	422267.2		
		Iron (Fe)	7439-89-6	0.00023	24000	10387.32		
		Phosporus (P)	7723-14-0	3E-06	300	135.4868		
		Zinc (Zn)	7440-66-6	7E-06	700	316.1359		
		Nickel (Ni)	7440-02-0	0	0	0		
		Silicon (Si)	7440-21-3	0	0	0		
		Magnesium (Mg)	7439-95-4	0	0	0		
		Tin (Sn)	7440-31-5	0	0	0		
		Lead Frame Total:				0.00959	1000000	433106.2
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0		
		Exter. Plating Sn	7440-31-5	0.0004373754	1000000	19752.87		
		External Plating Total:				0.0004373754	1000000	19752.87
		Inter. Plating Ni	7440-02-0	0	0	0		
		Inter. Plating Ag	7440-22-4	0.000218	1000000	9845.375		
		Internal Plating Total:				0.000218	1000000	9845.375
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000464	750000	20955.29		
		Tin (Sn)	7440-31-5	0	0	0		
		Lead (Pb)	7439-92-1	0	0	0		
		Silica (SiO2)	60676-86-0	0	0	0		
		Metal Oxide		0	0	0		
		Resin (EP)		0.000155	250000	7000.152		
Die Attach Total:				0.000619	1000000	27955.45		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.001368	130000	61781.99		
		Bromine (Br)	40039-93-8	0	0	0		
		Silica (SiO2)	60676-86-0	0.009047	860000	408583		
		Antimony Trioxide (Sb2O3)	1309-64-4	0	0	0		
		Metal Hydroxid		0	0	0		
		Carbon Black (C)	1333-86-4	0.000105	10000	4742.039		
		Encapsulation Total:				0.01052	1000000	475107.1
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	3.2E-05	1000000	1445.193		

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